

# ABSTRACT

A polyimide resin having phenolic hydroxyl radicals in  
5 its skeleton is prepared using a diamine bearing an aromatic  
ring having an amino radical attached thereto and another  
aromatic ring having a phenolic hydroxyl radical. The  
polyimide resin and a composition comprising the polyimide  
resin, an epoxy resin and a curing agent are suited for use  
10 as varnish, adhesive and adhesive film for which adhesion and  
heat resistance are required.